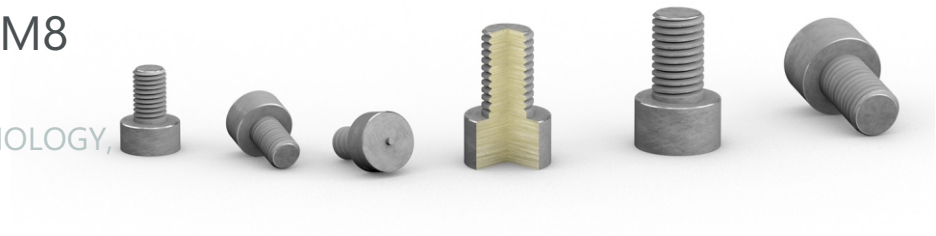
MTCON NECTIVITY

POWER TOWER M8

EXTERNAL THREAD,
SMD SOLDERING TECHNOLOGY,
WITHOUT CENTERING



COMMERCIAL DATA

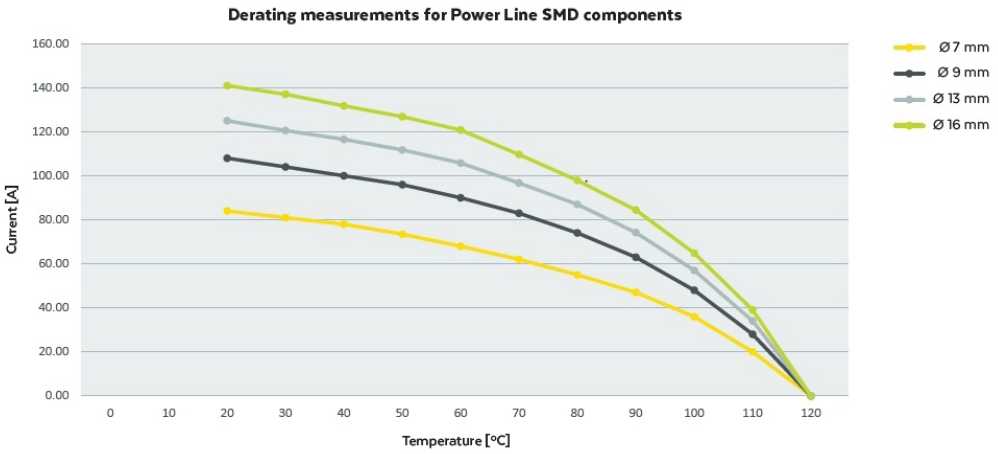
Part number	**01.6.0005**

Packing unit tape and reel - 1.6.0005.GU	**not available yet**
Customs tariff number	**85369010**
Mass	**13,96 g**
Country of origin	**DE (Germany)**

TECHNICAL DATA

Current carrying capacity	**ca. 180 A at 20°C / ca. 100 A at 85° C**
Material	**CuZn39Pb3**
Surface	**matt tinned**

Derating curves are snapshots under test condition!
Testing was undertaken using a two-layer circuit, with 70µm copper.



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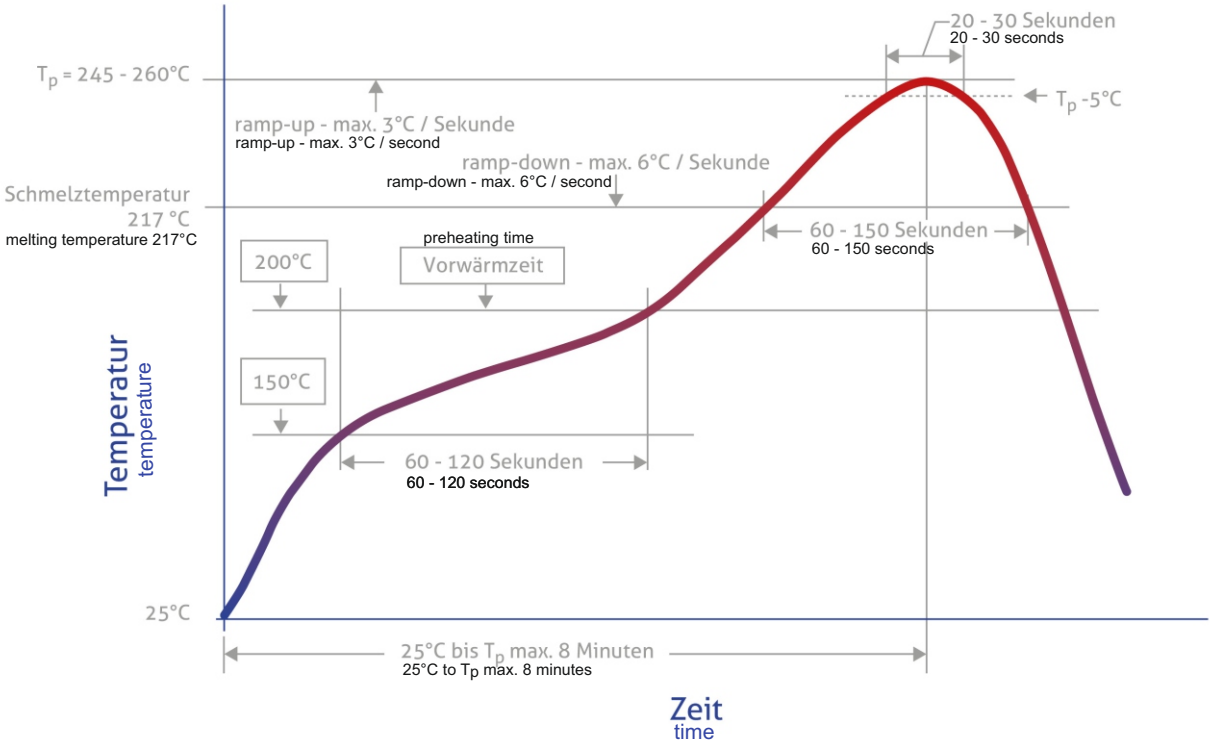
PROCESSING

Torque	**9,0 Nm**
Solder paste thickness	**150 µm**
Operating temperature	**-55°C to 150°C**

SOLDER PROFILE



Reflow Temperatur in Abhängigkeit der Leiterplattendicke:

Reflow temperature depending on the thickness of printed circuit board:

Eigenschaften properties	Volumen mm³ <350 volume mm³ < 350	Volumen mm³ 350-2000 volume mm³ 350-2000	Volumen mm³ >2000 volume mm³ > 2000
Leiterplattendicke (Bleifrei) < 1.6 mm PCB thickness (lead free) < 1.6 mm	260 °C	260 °C	260 °C
Leiterplattendicke (Bleifrei) 1.6 mm - 2.5 mm PCB thickness (lead free) 1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
Leiterplattendicke (Bleifrei) ≥ 2.5 mm PCB thickness (lead free) ≥ 2.5 mm	250 °C	245 °C	245 °C

mit Bezug auf IPC/JEDEC J-STD-020D
regarding IPC/JEDEC J-STD-020D

CONFORMITY

- RoHS compliant

RoHS COMPLIANT

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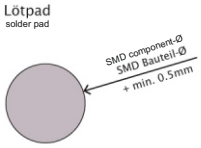
TAPE AND REEL

not available yet

LAYOUT



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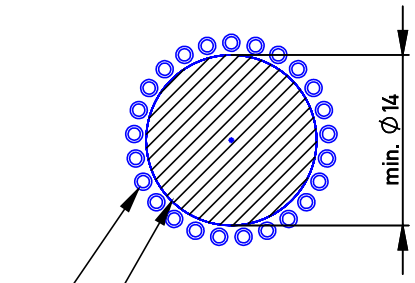
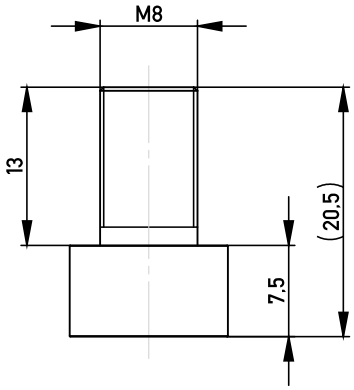
LAYOUT

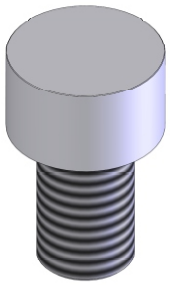
Verpackung / *packaging*	Artikelnummer / *part number*
lose / *bulk*	01.6.0005
tape and reel	not available

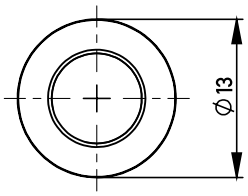


Empfehlung Lötpad / *recommendation solder pad*
vollflächiges Pad min. 0.5mm umlaufend größer als Element /
full-face pad all round min. 0.5mm bigger than the element

optionale DK-Bohrungen umlaufend um das Pad - für höhere Stromtragfähigkeit /
optional plated holes around the pad - for higher current ratings







RoHS COMPLIANT

Ausführung: SMD
Max. Drehmoment: 9,0 Nm
Gewicht: 13,96 g
Technische Änderungen vorbehalten

execution: SMD
max. torque: 9,0 Nm
weight: 13,96 g
technical subject to change

Werkstoff / *material*	CuZn39Pb3	Toleranz / *tolerance*	Maßstab / *scale* 2:1
Oberfläche / *surface plating*	matt verzinnt / *mat tin-plated*	DIN ISO 2768-mH	Zeichnungsnummer / *drawing number* 01.6.0005
Prozessbedingte Fehlstellen in Galvanik möglich! *imperfections during electro plating process possible!*		all dimensions in mm	

	Datum / *date*	Name / *name*
Bearb. / *drawer*	13.02.2014	
gepr. / *auth.*		
geän. / *mod.*		

Benennung / description

Power Tower M8
SMD, 13er rund, ohne Zentrierzapfen
SMD; thirteens round, without centering pin

Index	Änderung / *modification*	Datum / *date*	Name / *name*
	REACH entfernen	17.07.2018	
A	Neuerstellung	13.02.2014	

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